Title (en)

METHODS OF MECHANICAL AND ELECTRICAL SUBSTRATE CONNECTION

Title (de)

VERFAHREN ZUR MECHANISCHEN UND ELEKTRISCHEN VERBINDUNG EINES SUBSTRATES

Title (fr)

PROCEDES DE CONNEXION ELECTRIQUE ET MECANIQUE DE SUBSTRATS

Publication

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Application

EP 96906318 A 19960208

Priority

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Abstract (en)

[origin: US5537738A] The disclosure describes a method of attaching and electrically connecting first and second planar substrates, wherein the first and second substrates have inwardly-facing surfaces with matching patterns of bond pads. The method includes adjusting a wire bonder's tear length to a setting which leaves a projecting tail of severed bond wire at a terminating wedge bond connection. Further steps include making a wedge bond to an individual bond pad of the first planar substrate with bond wire from the wire bonder, and then severing the bond wire adjacent said wedge bond. The adjusted tear length of the wire bonder results in a tail of severed bond wire which projects from said wedge bond and said individual bond pad. Subsequent steps include positioning the first and second planar substrates with their inwardly facing surfaces facing each other, aligning the matching bond pad patterns of the first and second planar substrates, and pressing the first and second planar substrates against each other. The bond wire tail deforms between the bond pads of the first and second planar substrates to conductively bond therebetween.

IPC 1-7

H01J 9/26

IPC 8 full level

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C-Set (source: EP US)

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4. H01L 2224/45015 + H01L 2924/20753
5. H01L 2224/45015 + H01L 2924/00
6. H01L 2224/45124 + H01L 2924/00015
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